

1. (Proposed) An integrated circuit with a micromechanical element comprising:
  - a semiconductor substrate;
  - a micromechanical sensor element formed on the semiconductor substrate and comprising a microengineered movable element;
  - a logic circuit formed on the semiconductor substrate; and
  - a semiconductor visual display element formed on the semiconductor substrate; wherein the sensor element is electrically connected to the logic circuit, and the logic circuit is electrically connected to the semiconductor visual display element; and  
wherein the sensor element, the logic circuit and the semiconductor visual display  
are integrated together on the semiconductor substrate.

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